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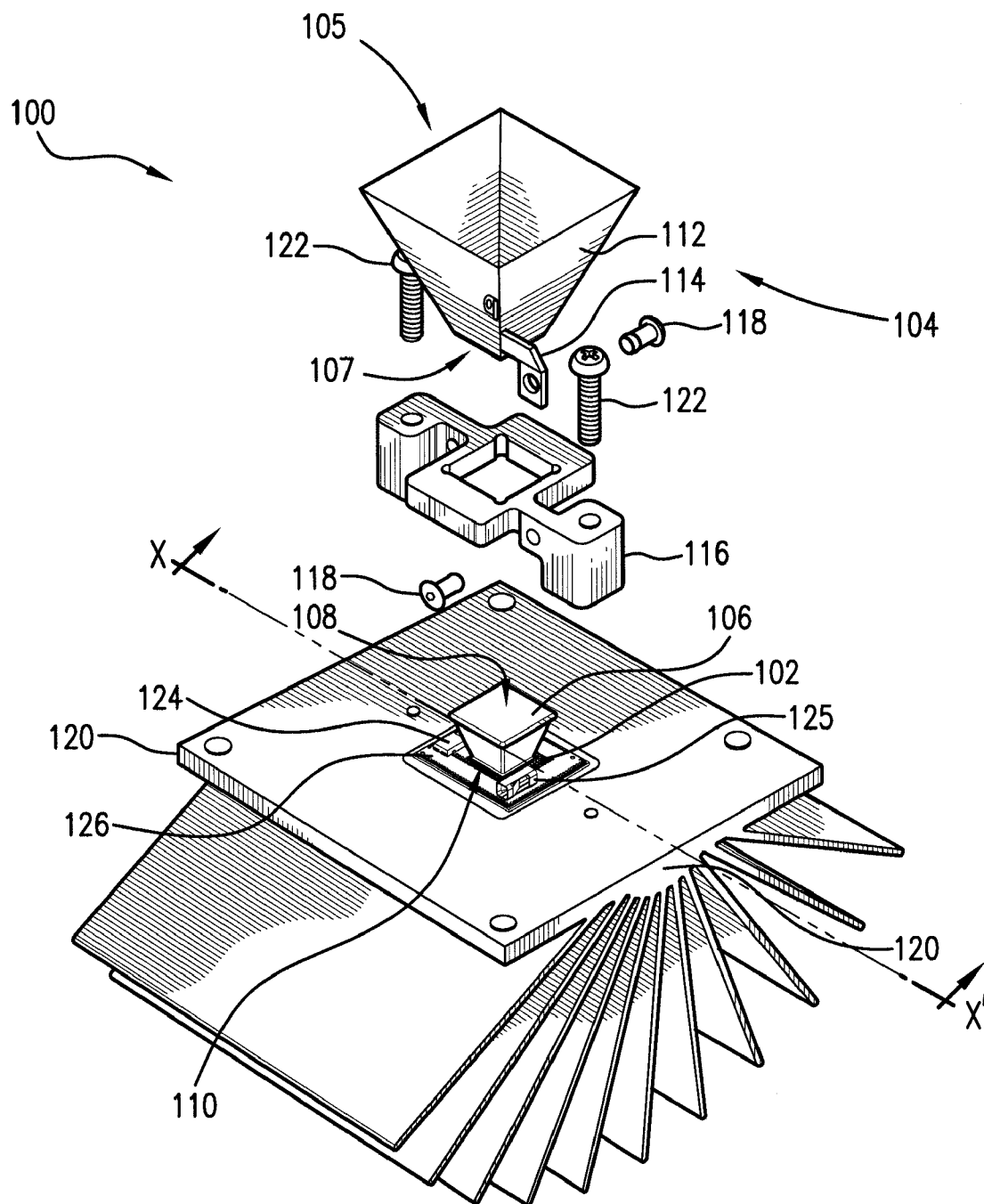


FIG. 1

FIG. 2

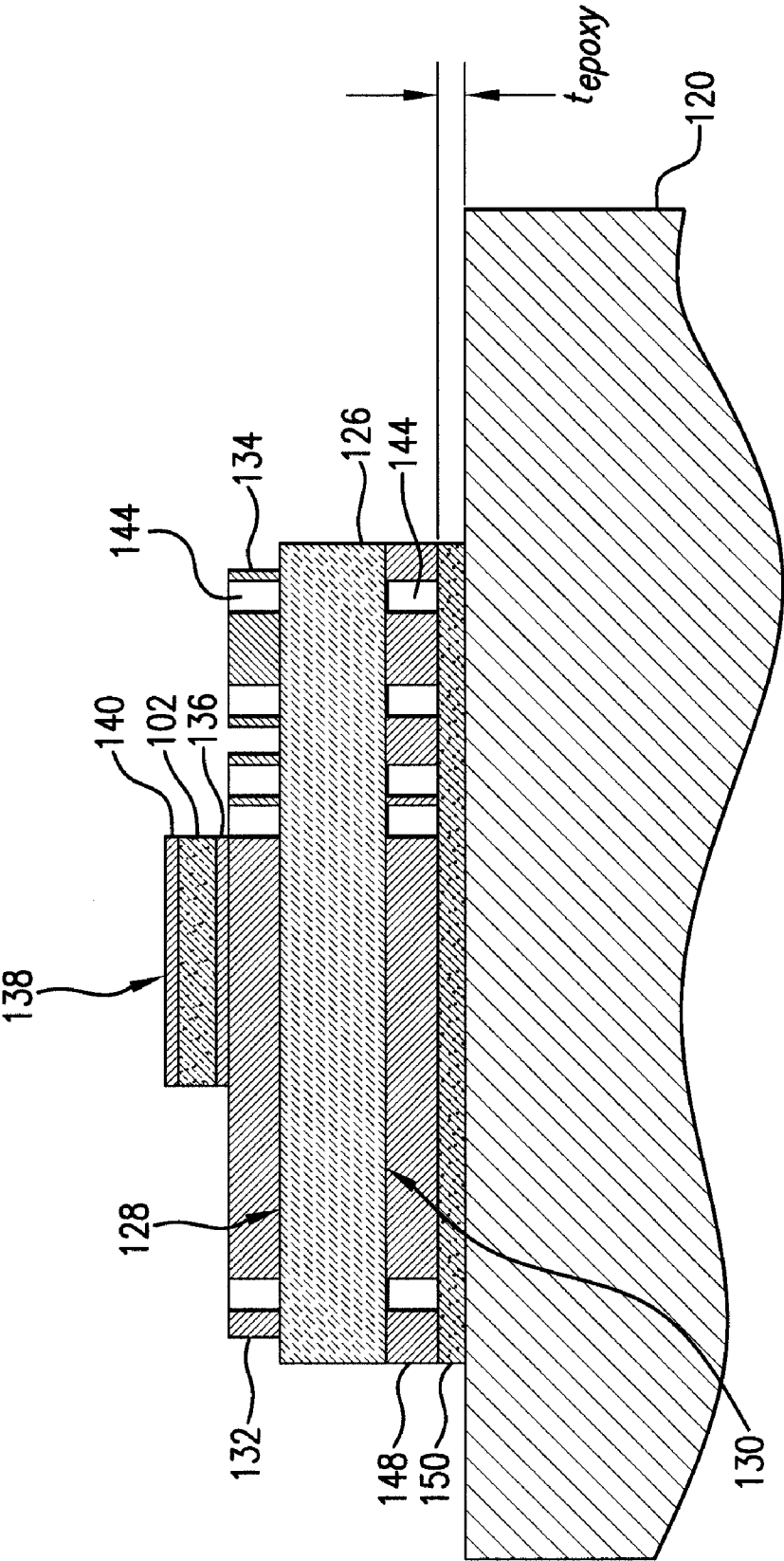


FIG.3

CONCENTRATED PHOTOVOLTAIC SYSTEM RECEIVER FOR III-V SEMICONDUCTOR SOLAR CELLS

RELATED APPLICATIONS

[0001] The disclosure of this application is related to co-pending U.S. application Ser. No. 12/246,295, filed on Oct. 6, 2008; U.S. application Ser. No. 12/069,642 filed on Feb. 11, 2008; U.S. application Ser. No. 12/254,369, filed on Nov. 4, 2008 which is a divisional of U.S. Ser. No. 12/069,642; U.S. application Ser. No. 11/849,033, filed on Aug. 31, 2007; U.S. application Ser. No. 11/830,576, filed on Jul. 30, 2007; and U.S. application Ser. No. 11/500,053, filed on Aug. 7, 2006, the contents of which are incorporated herein by reference in their entirety.

FIELD OF THE INVENTION

[0002] The present application is directed to a solar cell receiver, more particularly, to a solar cell receiver including a solar cell, metallized ceramic substrate and a heat sink.

BACKGROUND

[0003] Historically, solar power (both in space and terrestrially) has been predominantly provided by silicon solar cells. In the past several years, however, high-volume manufacturing of high-efficiency III-V compound semiconductor multijunction solar cells for space applications has enabled the consideration of this alternative technology for terrestrial power generation. Compared to silicon, III-V compound semiconductor multijunction cells are generally more radiation resistant and have greater energy conversion efficiencies, but they tend to cost more to manufacture. Some current III-V compound semiconductor multijunction cells have energy efficiencies that exceed 27%, whereas silicon technologies generally reach only about 17% efficiency. Under concentration, some current III-V compound semiconductor multijunction cells have energy efficiencies that exceed 37%.

[0004] Generally speaking, the multijunction cells are of n-on-p polarity and are composed of a vertical stack of InGaP/(In)GaAs/Ge semiconductor structures. The III-V compound semiconductor multijunction solar cell layers are typically grown via metal-organic chemical vapor deposition (MOCVD) on germanium (Ge) substrates. The use of the Ge substrate permits a junction to be formed between n- and p-type Ge, thereby utilizing the substrate for forming the bottom or low band gap subcell. The solar cell structures are typically grown on 100-mm diameter Ge wafers with an average mass density of about 86 mg/cm². In some processes, the epitaxial layer uniformity across a platter that holds 12 or 13 Ge substrates during the MOCVD growth process is better than 99.5%. Each wafer typically yields two large-area solar cells. The cell areas that are processed for production typically range from 26.6 to 32.4 cm². The epitaxial wafers can subsequently be processed into finished solar cell devices through automated robotic photolithography, metallization, chemical cleaning and etching, antireflection (AR) coating, dicing, and testing processes. The n- and p-contact metallization is typically comprised of predominately Ag with a thin Au cap layer to protect the Ag from oxidation. The AR coating is a dual-layer TiO_x/Al₂O₃ dielectric stack, whose spectral reflectivity characteristics are designed to minimize reflection at the coverglass-interconnect-cell (CIC) or solar cell

assembly (SCA) level, as well as, maximizing the end-of-life (EOL) performance of the cells.

[0005] In some compound semiconductor multijunction cells, the middle cell is an InGaAs cell as opposed to a GaAs cell. The indium concentration may be in the range of about 1.5% for the InGaAs middle cell. In some implementations, such an arrangement exhibits increased efficiency. The advantage in using InGaAs layers is that such layers are substantially better lattice-matched to the Ge substrate.

SUMMARY

[0006] According to an embodiment, a solar cell receiver for converting solar energy to electricity includes a ceramic substrate, a solar cell and a heat sink. The ceramic substrate has a first metallized surface and an opposing second metallized surface. The first metallized surface of the ceramic substrate has separated conductive regions. The solar cell has a conductive first surface connected to a first one of the conductive regions of the ceramic substrate and an opposing second surface having a conductive contact area connected to a second one of the conductive regions. The heat sink is bonded to the second metallized surface of the ceramic substrate with a highly thermally conductive attach media, such as a metal-filled epoxy adhesive or solder.

[0007] According to another embodiment, a solar cell receiver for converting solar energy to electricity includes a ceramic substrate, a solar cell, a bypass diode and a heat sink. The ceramic substrate has a first metallized surface and an opposing second metallized surface. The first metallized surface of the ceramic substrate has separated conductive regions. The solar cell has an anode terminal electrically connected to a first one of the conductive regions of the ceramic substrate and a cathode terminal electrically connected to a second one of the conductive regions. The bypass diode is connected across the first and second conductive regions of the ceramic substrate in parallel with the solar cell. The heat sink is bonded to the second metallized surface of the ceramic substrate with a highly thermally conductive attach media, such as a metal-filled epoxy adhesive or solder.

[0008] According to another embodiment, a solar cell receiver is manufactured by providing a ceramic substrate having a first metallized surface and an opposing second metallized surface, the first metallized surface having separated conductive regions. A conductive first surface of a solar cell is connected to a first one of the conductive regions of the ceramic substrate and a conductive contact area of an opposing second surface of the solar cell is connected to a second one of the conductive regions. A heat sink is bonded to the second metallized surface of the ceramic substrate with a highly thermally conductive attach media, such as a metal-filled epoxy adhesive or solder.

[0009] Of course, the present invention is not limited to the above features and advantages. Those skilled in the art will recognize additional features and advantages upon reading the following detailed description, and upon viewing the accompanying drawings.

BRIEF DESCRIPTION OF THE DRAWINGS

[0010] FIG. 1 is a partially exploded perspective view of an embodiment of a solar cell receiver including a solar cell, a metallized ceramic substrate and a heat sink.

[0011] FIG. 2 shows the solar cell and the metallized ceramic substrate of FIG. 1 in more detail.

[0012] FIG. 3 is a cross-sectional view of the solar cell, the metallized ceramic substrate and the heat sink shown in FIG. 1.

DETAILED DESCRIPTION

[0013] Details of the present invention will now be described including exemplary aspects and embodiments thereof. Referring to the drawings and the following description, like reference numbers are used to identify like or functionally similar elements, and are intended to illustrate major features of exemplary embodiments in a highly simplified diagrammatic manner. Moreover, the drawings are not intended to depict every feature of the actual embodiment nor the relative dimensions of the depicted elements, and are not drawn to scale.

[0014] Solar cell receivers include a solar cell for converting solar energy into electricity. In various implementations described herein, a triple-junction III-V compound semiconductor solar cell is employed, but other types of solar cells could be used depending upon the application. Solar cell receivers often contain additional components, e.g., connectors for coupling to an output device or other solar cell receivers.

[0015] For some applications, a solar cell receiver may be implemented as part of a solar cell module. A solar cell module may include a solar cell receiver and a lens coupled to the solar cell receiver. The lens is used to focus received light onto the solar cell receiver. As a result of the lens, a greater concentration of solar energy can be received by the solar cell receiver. In some implementations, the lens is adapted to concentrate solar energy by a factor of 400 or more. For example, under 500-Sun concentration, 1 cm² of solar cell area produces the same amount of electrical power as 500 cm² of solar cell area would, without concentration. The use of concentration, therefore, allows substitution of cost-effective materials such as lenses and mirrors for the more costly semiconductor cell material. Two or more solar cell modules may be grouped together into an array. These arrays are sometimes referred to as “panels” or “solar panels.”

[0016] FIG. 1 illustrates an embodiment of a solar cell receiver 100 including a solar cell 102. In one embodiment, the solar cell 102 is a triple-junction III-V compound semiconductor solar cell which comprises a top cell, a middle cell and a bottom cell arranged in series. In another embodiment, the solar cell 102 is a multijunction solar cell having n-on-p polarity and is composed of InGaP/(In)GaAs III-V compounds on a Ge substrate. In each case, the solar cell 102 is positioned to receive focused solar energy from a secondary optical element 104.

[0017] The secondary optical element 104 is positioned between the solar cell 102 and a primary focusing element (not shown) such as a lens. The secondary optical element 104 is generally designed to collect solar energy concentrated by the corresponding lens toward the upper surface of the solar cell 102. The secondary optical element 104 includes an entry aperture 105 that receives light beams from the corresponding lens and an exit aperture 107 that transmits the light beams to the solar cell 102. The secondary optical element 104 includes an intermediate region 112 between the apertures 105, 107. Under ideal conditions, the lens associated with the secondary optical element 104 focuses the light directly to the solar cell 102 without the light hitting against the secondary optical element 104.

[0018] In most circumstances, the lens does not focus light directly on the solar cell 102. This may occur due to a variety of causes, including but not limited to chromatic aberration of a refractive lens design, misalignment of the solar cell 102 relative to the lens during construction, misalignment during operation due to tracker error, structural flexing, and wind load. Thus, under most conditions, the lens focuses the light such that it reflects off the secondary optical element 104. The difference between an ideal setup and a misaligned setup may be a minor variation in the positioning of the lens of less than 1°.

[0019] The secondary optical element 104 therefore acts as a light spill catcher to cause more of the light to reach the solar cell 102 in circumstances when the corresponding lens does not focus light directly on the solar cell 102. The secondary optical element 104 can include a reflective multi-layer intermediate region such as the kind disclosed in U.S. patent application Ser. No. 12/402,814 filed on Mar. 12, 2009, the content of which is incorporated herein by reference in its entirety. The reflective multi-layer intermediate region can be formed from different materials and have different optical characteristics so that the reflectivity of the light beams off secondary optical element 104 and transmitted to the solar cell 102 optimizes the aggregate irradiance on the surface of the solar cell 102 over the incident solar spectrum. For example, in some implementations, the inner surface of the body 112 of the secondary optical element 104 can be coated with silver or another material for high reflectivity. In some cases, the reflective coating is protected by a passivation coating such as SiO₂ to protect the secondary optical element 104 against oxidation, tarnish or corrosion.

[0020] The body 112 of the secondary optical element 104 has one or more mounting tabs 114 for attaching the body 112 to a bracket 116 via one or more fasteners 118. The bracket 116 is provided for mounting the secondary optical element 104 to a heat sink 120 via one or more fasteners 122. The bracket 116 is thermally conductive so that heat energy generated by the secondary optical element 104 during operation can be transferred to the heat sink 120 and dissipated. As shown in this implementation, the secondary optical element 104 has four reflective walls. In other implementations, different shapes (e.g., three-sided to form a triangular cross-section) may be employed. The secondary optical element 104 can be made of metal, plastic, or glass or other materials.

[0021] In one embodiment as shown in FIG. 2, a concentrator 106 is disposed between the exit aperture 107 of the secondary optical element 104 and the solar cell 102. The concentrator 106 is preferably glass and has an optical inlet 108 and an optical outlet 110. In one embodiment, the concentrator 106 is solid glass. The concentrator 106 amplifies the light exiting the secondary optical element 104 and directs the amplified light toward the solar cell 102. In some implementations, the concentrator 106 has a generally square cross section that tapers from the inlet 108 to the outlet 110. In some implementations, the optical inlet 108 of the concentrator 106 is square-shaped and is about 2 cm×2 cm and the optical outlet 110 is about 0.9 cm×0.9 cm. The dimensions of the concentrator 106 may vary with the design of the solar cell module and the receiver. For example, in some implementations the dimensions of the optical outlet 110 are approximately the same as the dimensions of the solar cell 102. In one embodiment, the concentrator 106 is a 2× concentrator. The bottom surface of the concentrator 106 can be directly attached to the upper surface of the solar cell 102 using an

adhesive such as a silicone adhesive. The solar cell **102** converts the incoming sunlight directly into electricity by the photovoltaic effect.

[0022] A bypass diode **124** is connected in parallel with the solar cell **102**. In some implementations, the diode **124** is a semiconductor device such as a Schottky bypass diode or an epitaxially grown p-n junction. For purposes of illustration, the bypass diode **124** is a Schottky bypass diode. External connection terminals **125** and **127** are provided for connecting the solar cell **102** and the diode **124** to other devices, e.g., adjacent solar cell receivers (not shown).

[0023] The functionality of the bypass diode **124** can be appreciated by considering multiple solar cells **102** connected in series. Each solar cell **102** can be envisioned as a battery, with the cathode of each of the diodes **124** being connected to the positive terminal of the associated "battery" and the anode of each of the diodes **124** being connected to the negative terminal of the associated "battery." When one of the serially-connected solar cell receivers **100** becomes damaged or shadowed, its voltage output is reduced or eliminated (e.g., to below a threshold voltage associated with the diode **124**). Therefore, the associated diode **124** becomes forward-biased, and a bypass current flows only through that diode **124** (and not the solar cell **102**). In this manner, the non-damaged or non-shadowed solar cell receivers **100** continue to generate electricity from the solar energy received by those solar cells. If not for the bypass diode **124**, substantially all of the electricity produced by the other solar cell receivers would pass through the shadowed or damaged solar cell receiver, destroying it, and creating an open circuit within, e.g., the panel or array. The solar cell receiver **100** also includes a ceramic substrate **126** such as an alumina substrate for mounting of the solar cell **102** and the heat sink **120** for dissipating heat generated by the solar cell **102** during operation.

[0024] FIG. 2 illustrates the solar cell **102** and the ceramic substrate **126** in more detail. The ceramic substrate **126** has metallized upper and lower surfaces **128** and **130**. Both surfaces **128** and **130** of the ceramic substrate **126** are metallized. The upper surface **128** is metallized to provide electrical contacts; the bottom surface **130** has an approximately equal metallization to prevent warpage of the ceramic/metal assembly due to differential thermal expansion. The bottom metallization is bonded to the mounting surface of the heat sink **120** with a thermally conductive adhesive to reduce the thermal resistance of the interface between the two components. The resulting low thermal resistance of the assembly from the solar cell **102** to the heat sink **120** keeps the solar cell **102** temperature low, which allows the receiver to generate more power, lowers strain at the interfaces due to mismatch of thermal expansion coefficients, and increases the lifetime of the components. A low thermal resistance between the solar cell **102** and the heat sink **120** may also prevent large temperature differences during thermal transients such as are experienced with sudden exposure of the solar cell **102** to concentrated sunlight.

[0025] The metallized upper surface **128** of the ceramic substrate **126** is in contact with the solar cell **102** and has separated conductive regions **132** and **134** for providing isolated electrically conductive paths to the solar cell **102**. The first conductive region **132** provides an anode electrical contact point for the solar cell **102** and the second conductive region **134** provides a cathode electrical contact point for the solar cell **102**. The solar cell **102** has a conductive lower surface **136** out-of-view in FIG. 2, but visible in the cross-

section of FIG. 3 that is positioned on and connected to the first conductive region **132** of the metallized upper surface **128** of the ceramic substrate **126**. The opposing upper surface **138** of the solar cell **102** has a conductive contact area **140** connected to the second conductive region **134** of the ceramic substrate **126**.

[0026] In one embodiment, the conductive lower surface **136** of the solar cell **102** forms an anode terminal of the solar cell **102** and the conductive contact area **140** disposed at the upper surface **138** of the solar cell **102** forms a cathode terminal. According to this embodiment, the conductive lower surface **136** of the solar cell **102** is positioned on the first conductive region **132** of the ceramic substrate **126** and electrically isolated from the second conductive region **134** to ensure proper operation of the solar cell **102**. In one embodiment, the first conductive region **132** of the ceramic substrate **126** is at least partly surrounded on three sides by the second conductive region **134** about a periphery region of the ceramic substrate **126**.

[0027] In one embodiment, the conductive contact area **140** disposed at the upper surface **138** of the solar cell **102** occupies the perimeter of the solar cell **102**. In some implementations, the upper conductive contact area **140** can be smaller or larger to accommodate the desired connection type. For example, the upper conductive contact area **140** may touch only one, two or three sides (or portions thereof) of the solar cell **102**. In some implementations, the upper conductive contact area **140** is made as small as possible to maximize the area that converts solar energy into electricity, while still allowing electrical connection. While the particular dimensions of the solar cell **102** will vary depending on the application, standard dimensions are about a 1 cm². For example, a standard set of dimensions can be about 12.58 mm×12.58 mm overall, about 0.160 mm thick, and a total active area of about 108 mm². For example, in a solar cell **102** that is approximately 12.58 mm×12.58 mm, the upper conductive contact area **140** can be about 0.98 mm wide and the active area can be about 10 mm×10 mm.

[0028] The upper conductive contact area **140** of the solar cell **102** may be formed of a variety of conductive materials, e.g., copper, silver, and/or gold-coated silver. In this implementation, it is the n-conductivity cathode (i.e. emitter) side of the solar cell **102** that receives light, and accordingly, the upper conductive contact area **140** is disposed on the cathode side of the solar cell **102**. In one embodiment, the upper conductive contact area **140** of the solar cell **102** is wire bonded to the second conductive region **134** of the metallized upper surface **128** of the ceramic substrate **126** via one or more bonding wires **142**.

[0029] The bypass diode couples the first conductive region **132** of the metallized upper surface **128** of the ceramic substrate **126** to the second conductive region **134**. In one embodiment, a cathode terminal of the bypass diode **124** is connected to the anode terminal of the solar cell **102** via the first conductive region **132** of the ceramic substrate **126** and an anode terminal of the bypass diode **124** is electrically connected to the cathode terminal of the solar cell **102** via the second conductive region **134** of the ceramic substrate **126**. The anode terminal of the solar cell **102** is formed by the lower conductive surface **136** of the solar cell **102** as described above and is out-of-view in FIG. 2, but visible in the cross-section of FIG. 3. The cathode terminal of the solar cell **102** is formed by the upper conductive contact area **140** of the solar cell **102** also as described above. The external connec-

tion terminals **125** and **127** disposed on the metallized upper surface **128** of the ceramic substrate **126** provide for electrical coupling of a device to the solar cell **102** and the bypass diode **124**. In some implementations, the connector terminals **125** and **127** correspond to anode and cathode terminals, and are designed to accept receptacle plugs (not shown) for connection to adjacent solar cell receivers.

[0030] The upper surface **128** of the ceramic substrate **126** can be metallized by attaching metallization layers **132** and **134** to the substrate. In one embodiment, holes **144** are formed in the metallization layers **132**, **134**. FIG. 2 shows the ceramic substrate **126** having two metallization layers **132** and **134** attached to the upper substrate surface **128** (the lower metallized surface is out of view in FIG. 2, but visible in the cross-section of FIG. 3). The metallization layers **132** and **134** are attached to the upper surface **128** of the ceramic substrate **126** by high temperature reactive bonding or other type of bonding process. The lower surface **130** of the ceramic substrate **126** can be similarly metallized and attached to the heat sink **120**.

[0031] FIG. 3 illustrates a cross-sectional view of the solar cell **102**, ceramic substrate **126** and heat sink **120** of the solar cell receiver **100** along the line labeled X-X' in FIG. 1. The secondary optical element **104**, light concentrator **106** and terminals **125**, **127** are not shown in FIG. 3 for ease of illustration. The upper and lower surfaces **128** and **130** of the ceramic substrate **126** are metallized. The upper metallized surface **128** of the substrate **126** has separated conductive regions **132** and **134** for providing electrically isolated anode and cathode connections to the solar cell **102** as described above.

[0032] The solar cell **102** has a conductive lower surface **136** connected to the conductive region **132** of the metallized upper surface **128** of the ceramic substrate **126**. In one embodiment, the conductive lower surface **136** of the solar cell **102** forms the anode terminal of the solar cell **102** and the conductive contact area **140** disposed at the upper surface **138** of the solar cell **102** forms the cathode terminal of the solar cell **102**. The conductive lower surface **136** of the solar cell **102** is positioned on the first conductive region **132** of the metallized upper surface **128** of the ceramic substrate **126** and electrically isolated from the second conductive region **134** to ensure proper operation of the solar cell **102**.

[0033] The lower surface **130** of the ceramic substrate **126** also has a metallization layer **148** that is bonded to the heat sink **120** with a highly thermally conductive attach media **150**, such as a metal-filled epoxy adhesive or solder. Filling an epoxy adhesive with metal increases the thermal conductivity of the interface between the ceramic substrate **126** and the heat sink **120**, further improving the heat transfer characteristics of the solar cell receiver **100**. In one embodiment, the highly thermally conductive attach media **150** is a metal-filled epoxy adhesive having a thickness t_{epoxy} of approximately 1 to 3 mils. The metal-filled epoxy adhesive can be applied to the lower metallized surface **130** of the ceramic substrate **126**, the heat sink **120** or both and then cured to bond the heat sink **120** to the substrate **126**. In one embodiment, the heat sink **120** is a single-piece extruded aluminum heat sink as shown in FIG. 1.

[0034] The solar cell receiver **100** can be manufactured by providing the metallized ceramic substrate **126** and connecting the conductive lower surface **136** of the solar cell **102** to the first conductive region **132** of the metallized upper surface **128** of the substrate **126**. The conductive contact area **140**

disposed at the upper surface **138** of the solar cell **102** is connected to the second conductive region **134** of the metallized upper surface **128** of the ceramic substrate **126**, e.g. via one or more bond wires **142**. The heat sink **120** is bonded to the lower metallized surface **130** of the ceramic substrate **126** with the metal-filled epoxy adhesive **150**.

[0035] Spatially relative terms such as “under”, “below”, “lower”, “over”, “upper”, and the like, are used for ease of description to explain the positioning of one element relative to a second element. These terms are intended to encompass different orientations of the device in addition to different orientations than those depicted in the figures. Further, terms such as “first”, “second”, and the like, are also used to describe various elements, regions, sections, etc and are also not intended to be limiting. Like terms refer to like elements throughout the description.

[0036] As used herein, the terms “having”, “containing”, “including”, “comprising” and the like are open ended terms that indicate the presence of stated elements or features, but do not preclude additional elements or features. The articles “a”, “an” and “the” are intended to include the plural as well as the singular, unless the context clearly indicates otherwise.

[0037] The present invention may be carried out in other specific ways than those herein set forth without departing from the scope and essential characteristics of the invention. The present embodiments are, therefore, to be considered in all respects as illustrative and not restrictive, and all changes coming within the meaning and equivalency range of the appended claims are intended to be embraced therein.

1. A solar cell receiver for converting solar energy to electricity, comprising:

- a ceramic substrate having a first metallized surface and an opposing second metallized surface, the first metallized surface having separated conductive regions;
- a semiconductor solar cell device having a conductive first surface connected to a first one of the conductive regions of the ceramic substrate and an opposing second surface having a conductive contact area connected to a second one of the conductive regions; and
- a heat sink bonded to the second metallized surface of the ceramic substrate with a thermally conductive attach media.

2. The solar cell receiver of claim 1, wherein an anode terminal of the semiconductor solar cell device is connected to the first conductive region of the ceramic substrate and a cathode terminal of the semiconductor solar cell device is connected to the second conductive region of the ceramic substrate.

3. The solar cell receiver of claim 1, wherein the first conductive region of the ceramic substrate is at least partly surrounded on three sides by the second conductive region of the ceramic substrate about a periphery region of the ceramic substrate.

4. The solar cell receiver of claim 1, wherein the conductive first surface of the semiconductor solar cell device is positioned on the first conductive region of the ceramic substrate and electrically isolated from the second conductive region of the ceramic substrate.

5. The solar cell receiver of claim 1, wherein the conductive contact area of the semiconductor solar cell device is wire bonded to the second conductive region of the ceramic substrate and electrically isolated from the first conductive region of the ceramic substrate.

6. The solar cell receiver of claim 1, wherein the semiconductor solar cell device is a multijunction solar cell.

7. The solar cell receiver of claim 1, wherein the heat sink is an extruded aluminum heat sink.

8. The solar cell receiver of claim 1, wherein the thermally conductive attach media comprises a metal-filled epoxy adhesive.

9. The solar cell receiver of claim 8, wherein the metal-filled epoxy adhesive has a thickness of approximately 1 to 3 mils.

10. The solar cell receiver of claim 1, further comprising a bypass diode coupling the first conductive region of the ceramic substrate to the second conductive region of the ceramic substrate.

11. The solar cell receiver of claim 1, further comprising a secondary optical element positioned adjacent to the semiconductor solar cell device and thermally connected to the heat sink, the second optical element including one or more reflective surfaces and an enlarged inlet that faces away from the semiconductor solar cell device and a smaller outlet that faces towards the semiconductor solar cell device.

12. The solar cell receiver of claim 11, further comprising a light concentrator arranged between the semiconductor solar cell device and the secondary optical element.

13. A solar cell receiver for converting solar energy to electricity, comprising:

a ceramic substrate having a first metallized surface and an opposing second metallized surface, the first metallized surface having separated conductive regions;

a semiconductor solar cell device having an anode terminal electrically connected to a first one of the conductive regions of the ceramic substrate and a cathode terminal electrically connected to a second one of the conductive regions;

a bypass diode connected across the first and second conductive regions of the ceramic substrate in parallel with the semiconductor solar cell device; and

a heat sink bonded to the second metallized surface of the ceramic substrate with a thermally conductive attach media.

14. The solar cell receiver of claim 13, wherein the anode terminal of the semiconductor solar cell device is positioned on the first conductive region of the ceramic substrate and electrically isolated from the second conductive region of the ceramic substrate.

15. The solar cell receiver of claim 13, wherein the cathode terminal of the semiconductor solar cell device is wire bonded

to the second conductive region of the ceramic and electrically isolated from the first conductive region of the ceramic substrate.

16. The solar cell receiver of claim 13, wherein the semiconductor solar cell device is a multijunction solar cell.

17. The solar cell receiver of claim 13, wherein the thermally conductive attach media comprises a metal-filled epoxy adhesive.

18. The solar cell receiver of claim 17, wherein the metal-filled epoxy adhesive has a thickness of approximately 1 to 3 mils.

19. The solar cell receiver of claim 13, wherein an anode terminal of the bypass diode is electrically connected to the cathode terminal of the semiconductor solar cell device and a cathode terminal of the bypass diode is connected to the anode terminal of the semiconductor solar cell device.

20. The solar cell receiver of claim 13, further comprising a secondary optical element with a tapered shape, the second optical element including an inlet that faces away from the semiconductor solar cell device and an outlet that faces towards the semiconductor solar cell device.

21. The solar cell receiver of claim 20, wherein the secondary optical element is thermally connected to the heat sink.

22. The solar cell receiver of claim 20, further comprising a concentrator positioned between the semiconductor solar cell device and the secondary optical element, the concentrator including a tapered shape with an enlarged first end facing towards the outlet of the secondary optical element and a reduced second end facing towards the semiconductor solar cell device.

23. A method of manufacturing a solar cell receiver, comprising:

providing a ceramic substrate having a first metallized surface and an opposing second metallized surface, the first metallized surface having separated conductive regions;

connecting a conductive first surface of a semiconductor solar cell device to a first one of the conductive regions of the ceramic substrate;

connecting a conductive contact area of an opposing second surface of the semiconductor solar cell device to a second one of the conductive regions;

and bonding a heat sink to the second metallized surface of the ceramic substrate with a metal-filled epoxy adhesive.

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